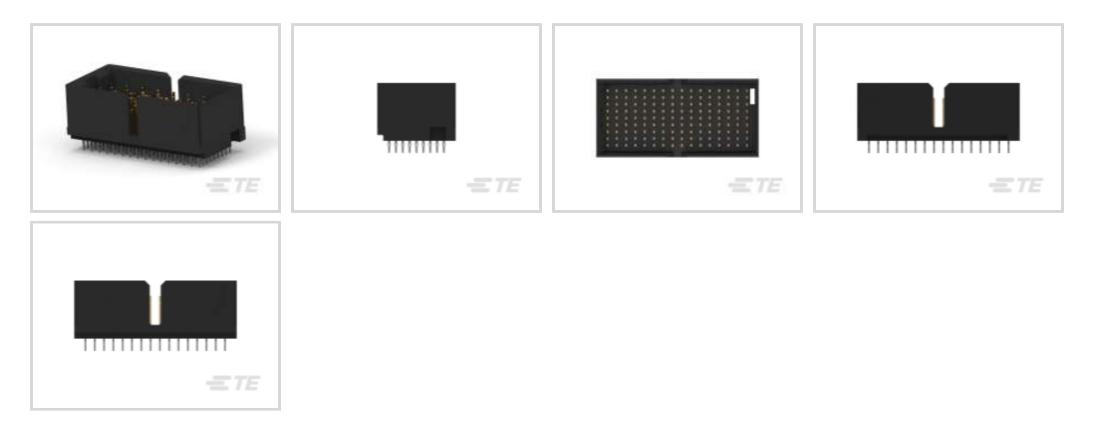


Z-PACK | Z-PACK TinMan

TE Internal #: 1934346-1 High Speed Backplane Connectors, 144 Position, Mating Alignment, Guide Slot Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Z-PACK TinMan

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Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors



Connector System: Board-to-Board Number of Positions: 144 Row-to-Row Spacing: 1.4 mm [.055 in] Mating Alignment: With

Mating Alignment Type: Guide Slot

Features



Product Type Features

Signal Arrangement	Differential
Connector System	Board-to-Board
PCB Connector Assembly Type	PCB Mount Header
Shroud Style	Fully Shrouded
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Pairs per Column	3
Number of Pairs	48
Stackable	No
Number of Signal Positions	96
Backplane Architecture	Traditional Backplane
Number of Positions	144
Number of Rows	9
Number of Columns	16

High Speed Backplane Connectors, 144 Position, Mating Alignment, Guide Slot Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Z-PACK TinMan



3 Mount Orientation Ve crical Characteristics	ertical
rical Characteristics	
pedance 10	Ω 00
erating Voltage 25	50 VAC
al Characteristics	
erential Impedance 10	Ω ΟC
mber of Differential Pairs per Column 3	
a Rate 10) Gb/s
Features	
nary Product Color Bl	lack
act Features	
ntact Mating Area Length 6	mm[.236 in]
3 Contact Termination Area Plating Material Thickness .5	μm[20 μin]
ntact Type Pi	in
ntact Mating Area Plating Material Thickness .70	'6 μm[29.92 μin]
ntact Mating Area Plating Material Go	iold
3 Contact Termination Area Plating Material Finish M	latte
ntact Shape & Form Re	ectangular
3 Contact Termination Area Plating Material Ti	in
ntact Base Material Ph	hosphor Bronze
ntact Current Rating (Max) .5	Ā
nination Features	
mination Post & Tail Length 2.	.5 mm[.098 in]
mination Method to Printed Circuit Board Th	hrough Hole - Press-Fit
nanical Attachment	
ide Hardware W	/ithout
ting Retention W	/ithout
3 Mount Alignment W	/ithout
3 Mount Retention W	/ith
3 Mount Retention Type Ad	ction/Compliant Tail
ting Alignment W	/ith
ting Alignment Type Gr	iuide Slot

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High Speed Backplane Connectors, 144 Position, Mating Alignment, Guide Slot Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Z-PACK TinMan



Housing Features	
Number of Shrouded Sides	4
End Wall Location	Dual
Housing Material	LCP (Liquid Crystal Polymer)
Centerline (Pitch)	1.9 mm[.075 in]
Dimensions	
Connector Length	33.15 mm
Connector Height	11.8 mm
Connector Width	16 mm
PCB Hole Diameter	.47 mm
Row-to-Row Spacing	1.4 mm[.055 in]
Usage Conditions	
Operating Temperature Range	-65 – 90 °C[-85 – 194 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
Agency/Standard	UL
Approved Standards	UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Box & Tube, Tube
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 202 (235) Candidate List Declared Against: JAN 20 (233)

High Speed Backplane Connectors, 144 Position, Mating Alignment, Guide Slot Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Z-PACK TinMan



Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

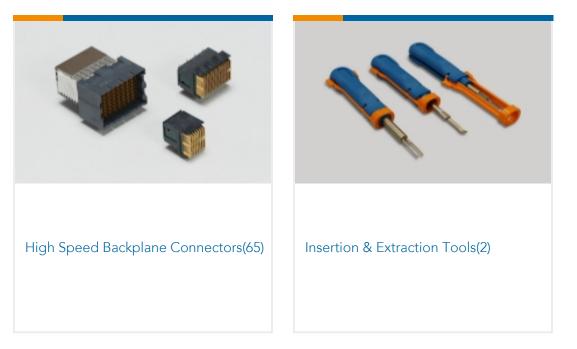
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts





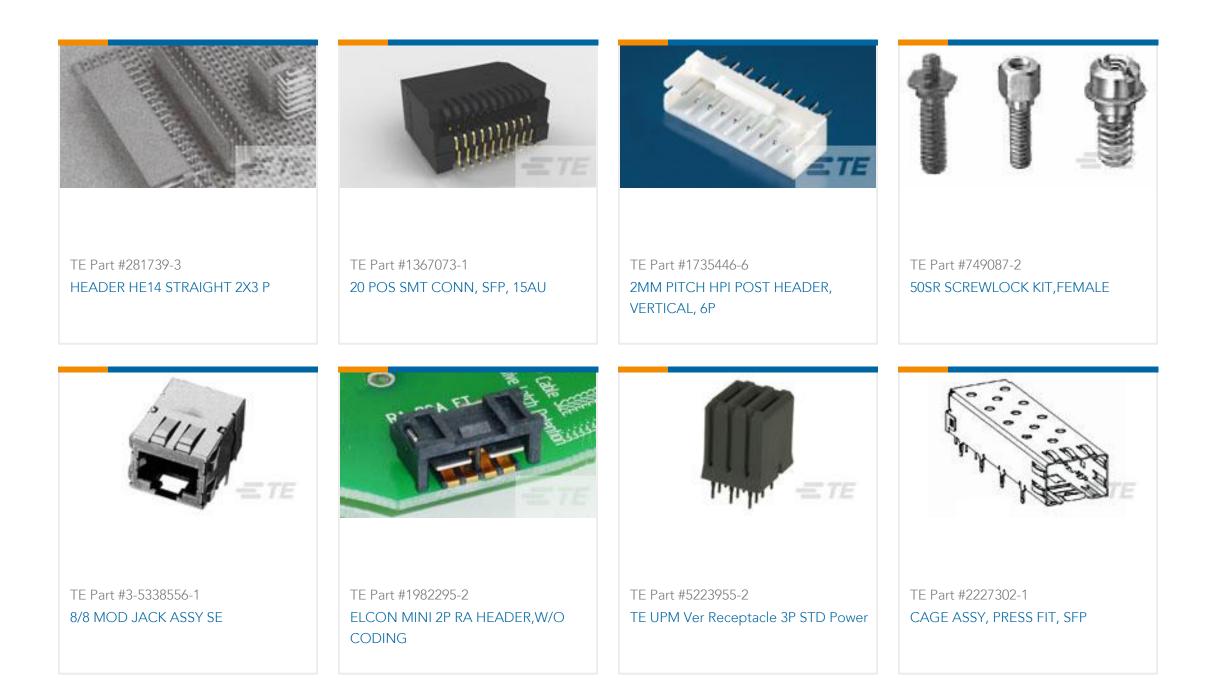
Also in the Series Z-PACK TinMan



Customers Also Bought

High Speed Backplane Connectors, 144 Position, Mating Alignment, Guide Slot Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Z-PACK TinMan





Documents

Product Drawings

Tin Man Header Assy 3x16 Double

English

CAD Files **Customer View Model**

ENG_CVM_1934346-1_B.3d_stp.zip

English

Customer View Model

ENG_CVM_1934346-1_B.2d_dxf.zip

English

Customer View Model

ENG_CVM_1934346-1_B.3d_igs.zip

English

3D PDF

English

By downloading the CAD file I accept and agree to the Terms and Conditions of use

Datasheets & Catalog Pages

High Speed Backplane Connectors catalog - Z-PACK TinMan High Speed, High Density Backplane Connector

English

Z-PACK TinMan High Speed High Density Backplane Connector Catalog 5-1773447-9

English

Product Specifications

Application Specification

English

High Speed Backplane Connectors, 144 Position, Mating Alignment, Guide Slot Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Z-PACK TinMan



Product Environmental Compliance TE Material Declaration

English